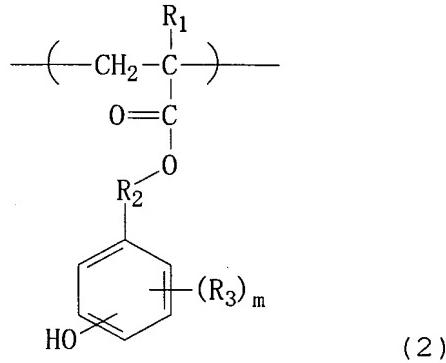
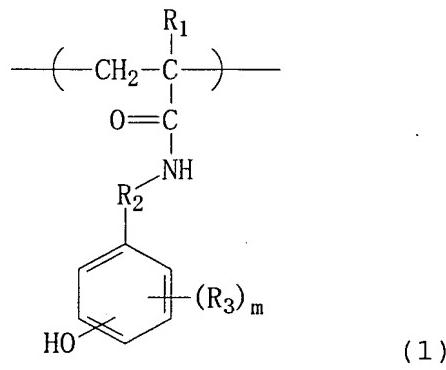


Claims

1. A positive radiation-sensitive resin composition comprising:

(A) a polymer containing structural units (a) represented by the following formula (1) and/or the following formula (2) and an acid-dissociable functional group (b),

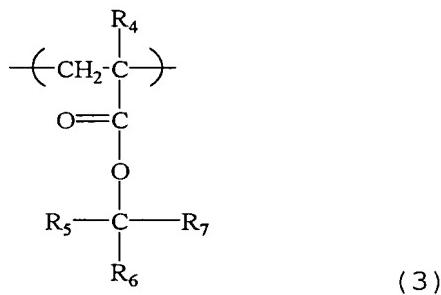


10 wherein R₁ is a hydrogen atom or a methyl group, R₂ is -(CH₂)_n-, n is an integer of 0 to 3, R₃ is an alkyl group of 1 to 4 carbon atoms, and m is an integer of 0 to 4,

(B) a component which generates an acid by irradiation with radiation, and

(C) an organic solvent.

2. The positive radiation-sensitive resin composition as claimed in claim 1, wherein the acid-dissociable functional group (b) is represented by the following formula (3):



wherein R_4 is a hydrogen atom or a methyl group, R_5 to R_7 are each an alkyl group of 1 to 4 carbon atoms, an alicyclic hydrocarbon group of 4 to 20 carbon atoms, an aromatic group or a substituted hydrocarbon group wherein at least one hydrogen atom in any one of these hydrocarbon groups is replaced with a polar group other than a hydrocarbon group, R_5 to R_7 may be the same or different, and when any two of R_5 to R_7 are alkyl groups or substituted alkyl groups, their alkyl chains may be bonded to each other to form an alicyclic hydrocarbon group of 4 to 20 carbon atoms or a substituted alicyclic hydrocarbon group.

3. The positive radiation-sensitive resin composition as claimed in claim 1, which is a composition for producing a plated shaped article.

5 4. The positive radiation-sensitive resin composition as claimed in claim 3, wherein the plated shaped article is a bump.

10 5. The positive radiation-sensitive resin composition as claimed in claim 1, wherein the component (B) is contained in an amount of 0.1 to 20 parts by weight based on 100 parts by weight of the component (A), and the component (C) is contained in an amount of 20 to 80 parts by weight based on the total weight 100 parts by
15 weight of the positive radiation-sensitive resin composition.

6. The positive radiation-sensitive resin composition as claimed in claim 1, which further
20 comprises an alkali-soluble resin other than the polymer (A).

7. The positive radiation-sensitive resin composition as claimed in claim 1, which further comprises an acid diffusion controller.

5 8. The positive radiation-sensitive resin composition as claimed in claim 1, wherein the component (B) is at least one compound selected from the group consisting of 4-t-butylphenyl·diphenylsulfonium trifluoromethanesulfonate, 4-t-
10 butylphenyl·diphenylsulfonium perfluoro-n-octanesulfonate, 4-t-butylphenyl·diphenylsulfonium pyrenesulfonate and 4,7-di-n-butoxynaphthyltetrahydrothiophenium trifluoromethanesulfonate.

15 9. A transfer film having a resin film composed of the positive radiation-sensitive resin composition of claim 1 on a support film.

10. The transfer film as claimed in claim 9,
20 wherein the resin film has a film thickness of 20 to 100 μm .

11. A process for producing a plated shaped article, comprising:

- (1) a step of forming a resin film composed of the positive radiation-sensitive resin composition of claim 1 on a wafer having a barrier metal layer,
- (2) a step of exposing the resin film and then 5 developing the resin film to form a pattern,
- (3) a step of depositing an electrode material by electroplating using the pattern as a mold, and
- (4) a step of stripping the remaining resin film and then removing the barrier metal by etching.